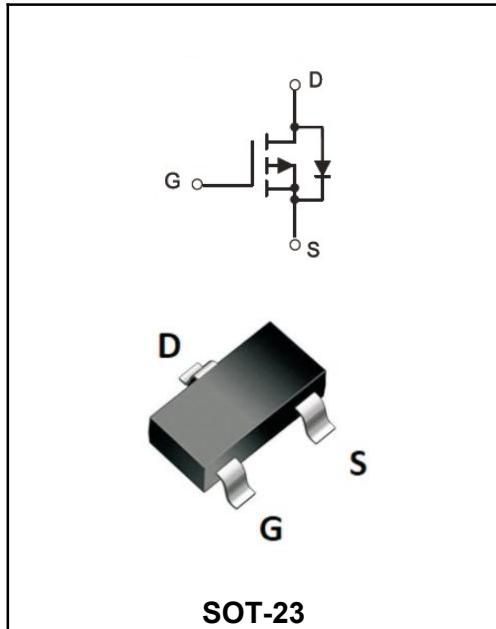


-20V P-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	-4.9A
V_{DSS}	-20V
$R_{DS(on)-typ}(@V_{GS}=-4.5V)$	< 38mΩ (Type: 32 mΩ)


Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Marking Code	
YFW2305A	A5SHB

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate - Source Voltage	V_{GS}	± 12	V
Continuous Drain Current, $V_{GS} @ -4.5V^1$ @ $T_A=25^\circ\text{C}$	I_D	-4.9	A
Continuous Drain Current, $V_{GS} @ -4.5V^1$ @ $T_A=70^\circ\text{C}$	I_D	-3.9	A
Pulsed Drain Current ²	I_{DM}	-14	A
Total Power Dissipation ³ @ $T_A=25^\circ\text{C}$	P_D	1.31	W
Total Power Dissipation ³ @ $T_A=70^\circ\text{C}$	P_D	0.84	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Thermal Resistance Junction-Ambient ¹	$R_{θJA}$	120	°C/W
Thermal Resistance Junction-Ambient ¹ ($t \leq 10\text{s}$)	$R_{θJA}$	95	°C/W

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	BV _{DSS}	-20	-	-	V
BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA	ΔBV _{DSS/ΔTJ}	-	-0.014	-	V/°C
Static Drain-Source On-Resistance ²	V _{GS} =-4.5V, I _D =-4.9A	R _{DS(ON)}	-	32	38	mΩ
	V _{GS} =-2.5V, I _D =-3.4A		-	45	55	
	V _{GS} =-1.8V, I _D =-2A			65	85	
Gate -Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	V _{GS(th)}	-0.4	-	-1.0	V
V _{Gs(th)} Temperature Coefficient		ΔV _{GS(th)}	-	3.95	-	mV/°C
Drain-Source Leakage Current	V _{DS} =-16V , V _{GS} =0V , T _J =25°C	I _{DSS}	-	-	-1	μA
	V _{DS} =-16V , V _{GS} =0V , T _J =55°C		-	-	-5	
Gate –Source Leakage Current	V _{GS} =±12V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Forward Transconductance	V _{DS} =-5V , I _D =-3A	g _{fs}	-	12.8	-	S
Total Gate Charge(-4.5V)	V _{DS} =-15V V _{GS} =-4.5V I _D =-3A	Q _g	-	10.2	14.3	nC
Gate-Source Charge		Q _{gs}	-	1.89	2.6	
Gate-Drain Charge		Q _{gd}	-	3.1	4.3	
Turn-on delay time	V _{DD} =-10V V _{GS} =-4.5V I _D =-3A R _G =3.3	t _{d(on)}	-	5.6	11.2	ns
Rise Time		T _r	-	40.8	73	
Turn-Off Delay Time		t _{d(OFF)}	-	33.6	67	
Fall Time		t _f	-	18	36	
Input Capacitance	V _{DS} =-15V V _{GS} =0V f=1MHz	C _{iss}	-	857	1200	pF
Output Capacitance		C _{oss}	-	114	160	
Reverse Transfer Capacitance		C _{rss}	-	108	151	
Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current	I _s	-	-	-4.9	A
Pulsed Source Current ^{2,4}		I _{SM}	-	-	-14	A
Diode Forward Voltage ²	V _{GS} =0V , I _s =-1A , T _J =25°C	V _{SD}	-	-	-1	V
Reverse Recovery Time	I _F =-3A, dI/dt=100A/μs, T _J =25°C	t _{rr}	-	21.8	-	ns
Reverse Recovery Charge		Q _{rr}	-	6.9	-	nC

Note :

1 .The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width Δ 300us , duty cycle Δ 2%

3.The power dissipation is limited by 150°C junction temperature

4.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

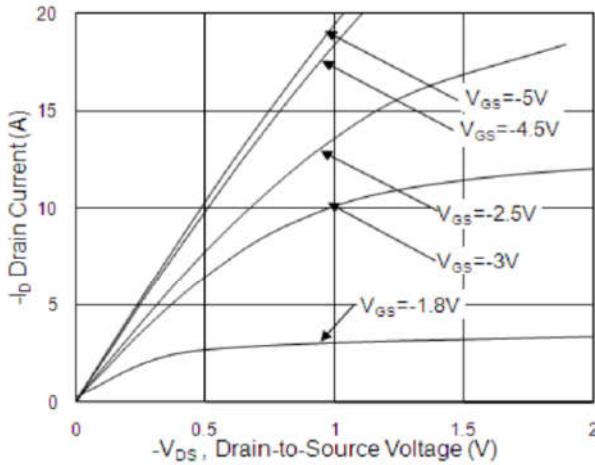


Fig.1 Typical Output Characteristics

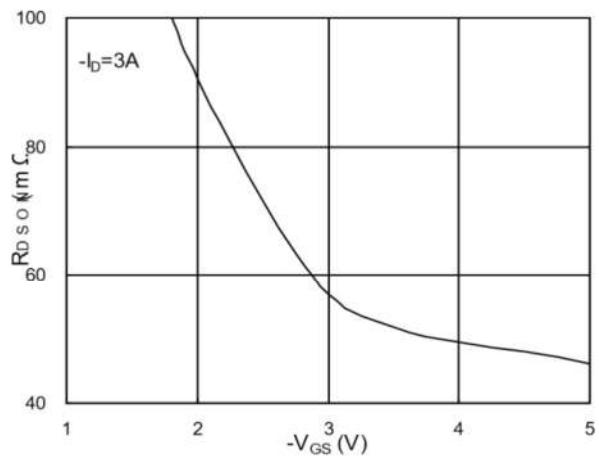


Fig.2 On-Resistance vs. G-S Voltage

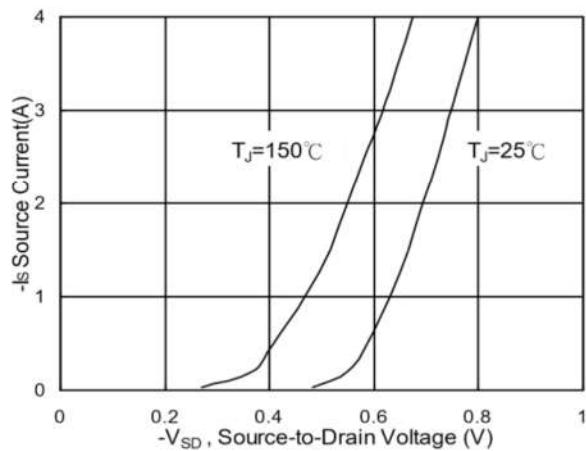


Fig.3 Forward Characteristics of Reverse

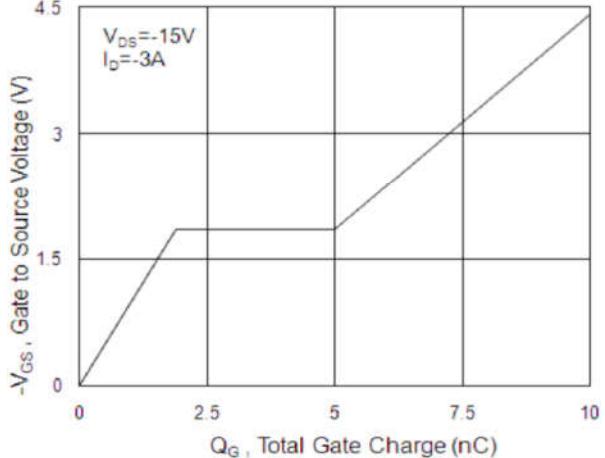


Fig.4 Gate-charge Characteristics

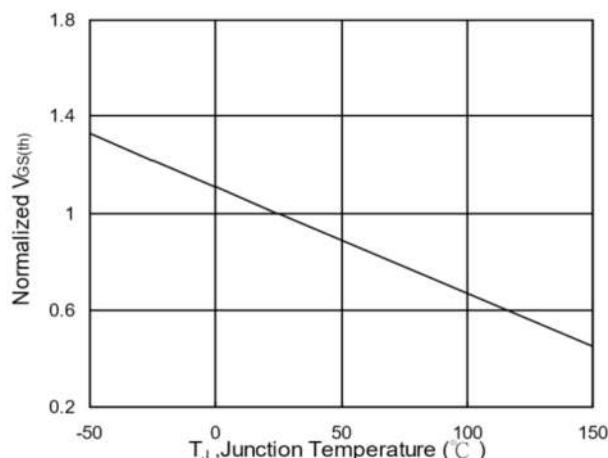


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

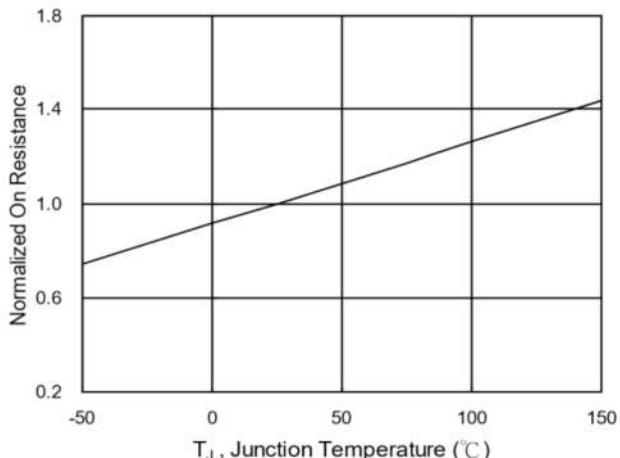


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

Ratings and Characteristic Curves

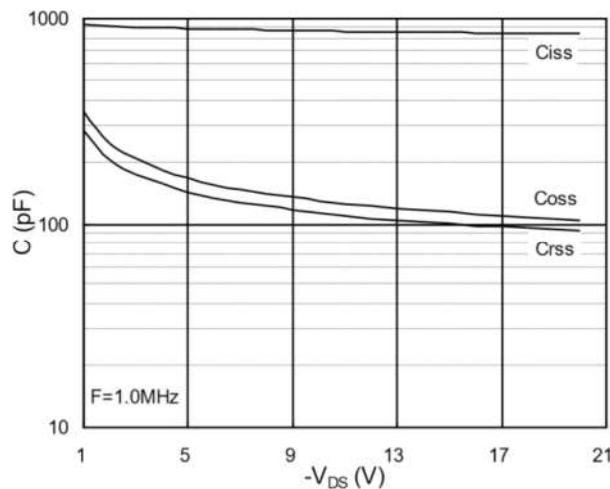


Fig.7 Capacitance

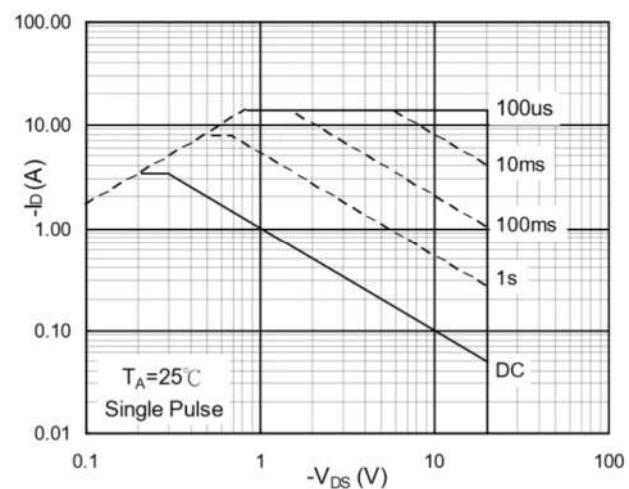


Fig.8 Safe Operating Area

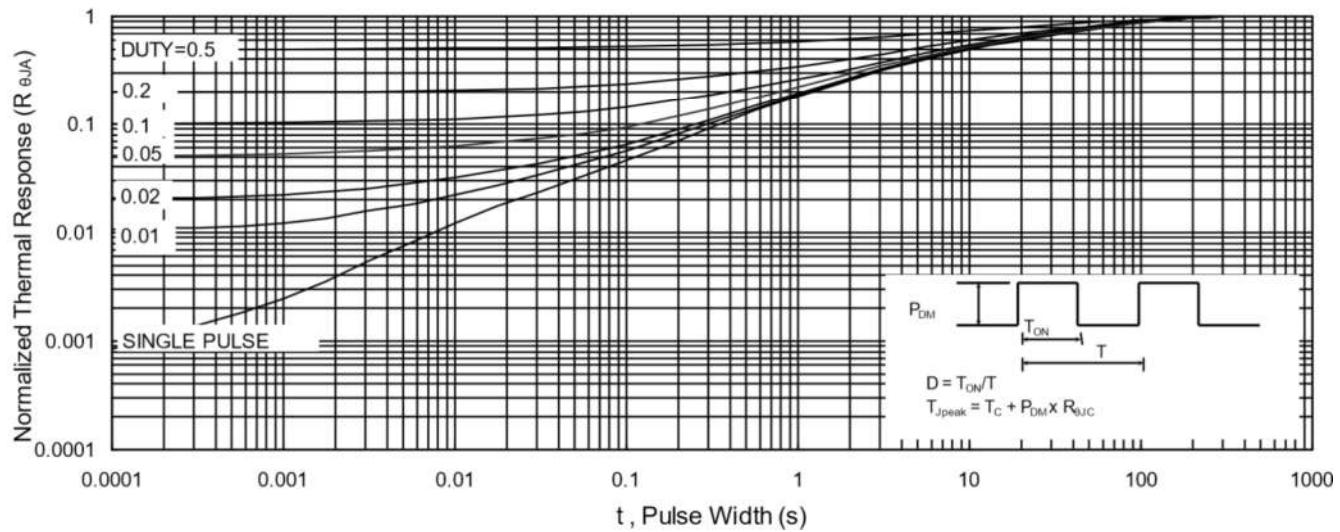


Fig.9 Normalized Maximum Transient Thermal Impedance

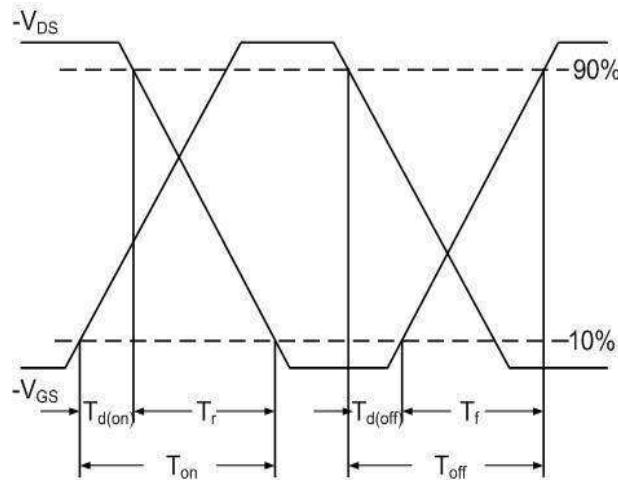


Fig.10 Switching Time Waveform

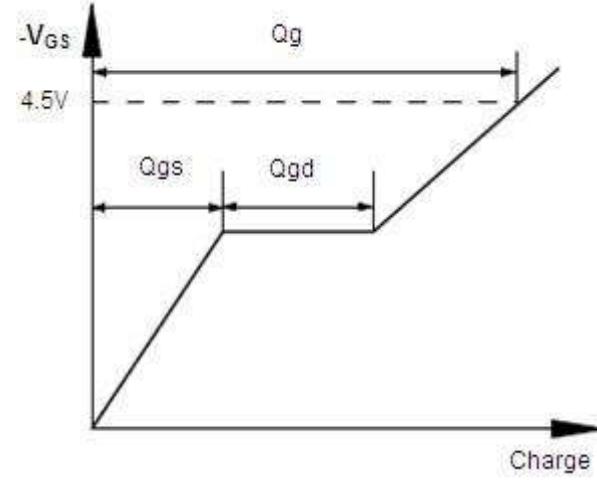


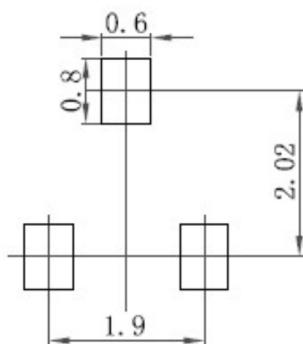
Fig.11 Gate Charge Waveform

Ordering information

Package	Packing Description	Base Quantity	Packing Quantity
SOT-23	Tape/Reel,7"reel	3000pcs/Reel	24000PCS/Box 120000PCS/Carton

Package Dimensions
SOT-23

Dim.	Millimeter (mm)		mil	
	Min.	Max.	Min.	Max.
A	0.9	1.15	35	45
A1	0.1		3.9	
bp	0.38	0.48	15	19
C	0.09	0.15	3.54	5.9
D	2.8	3.0	110	118
E	1.2	1.4	47	55
E	1.9		75	
E1	0.95		37	
HE	2.1	2.55	83	100
Lp	0.15	0.45	5.9	18
Q	0.45	0.55	18	22
v	0.2		7.9	
W	0.1		4	

The recommended mounting pad size


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